



Final Product/Process Change Notification

Document #:FPCN26124X

Issue Date:27 Feb 2025

Title of Change:	Qualification of Amkor Technology Malaysia as an additional Assembly and Test site for T10 80V Non-Auto MOSFET products packaged in SO8FL including material change of lead frame and mold compound.
Proposed First Ship date:	04 Jun 2025 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Changed material can be identified by assembly plant code
Change Category:	Test Change, Assembly Change
Change Sub-Category(s):	Material Change, Manufacturing Site Addition

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
None	AMKOR, Malaysia

Description and Purpose:

This Product Change Notification announces the qualification of Amkor Technology Malaysia as an additional assembly and test site for SO8FL discrete packaged products for Trench10 80V Non-auto MOSFET.

	From	To	
Assembly Site	onsemi Seremban	onsemi Seremban	Amkor
Lead Frame	TAMAC4 Cu	TAMAC4 Cu	C194 Cu
Mold Compound	G700LA type E	G700LA type E	G700LS

There is no product marking change as a result of this change.



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Reliability Data Summary:

QV DEVICE NAME: NTMFS2D1N08XT1G

RMS: S96602

PACKAGE: SO8FL

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=175°C, 100% max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta=175°C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=175°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST for surface mount pkgs only		0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0/90
Solderability	JSTD002	Ta = 245°C, 5 sec		0/45

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NTMFS3D0N08XT1G	NTMFS2D1N08XT1G
NTMFS4D0N08XT1G	NTMFS2D1N08XT1G
NTMFS2D1N08XT1G	NTMFS2D1N08XT1G
NTMFS2D5N08XT1G	NTMFS2D1N08XT1G
NTMFS3D5N08XT1G	NTMFS2D1N08XT1G